

L Number	Hits	Search Text	DB	Time stamp
1	6982	(csp (chip adj (size\$1 scale\$1) adj (package packaging device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 09:51
2	5007	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 09:53
3	893	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 12:02
4	10278	half adj thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 10:08
5	8	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and cutting) and (half adj thickness)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 10:08
6	467	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and cutting) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 10:11
7	32	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and cutting) and wafer) and ((seal\$3 dicing) near (tape film))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 12:03
8	1114	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and (cutting dicing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 12:03
9	64	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and (cutting dicing)) and ((seal\$3 dicing) near (tape film))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 12:04
10	32	((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and (cutting dicing)) and ((seal\$3 dicing) near (tape film)) not (((csp (chip adj (size\$1 scale\$1) adj (package packaging device))) ) and (process method)) and cutting) and wafer) and ((seal\$3 dicing) near (tape film))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/03 12:04